

## REMARKS

Reconsideration is respectfully requested.

By the above amendment Applicants have amended independent Claims 1 and 3 to more clearly and specifically claim the subject matter considered to be Applicants' invention. Specifically, the electrically conductive layer has been recited as being on "the outer surface" of the column and of the upper substrate. This amendment further differentiates the elements recited in the independent claims from the relied upon prior art references.

It is respectfully submitted that the rejections of Claims 1-5 over Fujimura et al. (U.S. Patent No. 5,973,763), and alternatively over Kurauchi et al. (U.S. Patent No. 5,917,572), are each improper because neither of these relied upon references disclose teach or show all of the limitations recited in the independent claims. The present invention is claimed as providing a supporting column that is extended vertically to a portion of the color filter of the upper substrate and is formed in the same position with the connect hole formed in the common line of the lower substrate. Also, the conductive layer is formed on the outer surface of the supporting column and on the surface of the upper substrate, which is joined to the common line and the supporting column through the contact hole so as to establish a signal interconnection between the lower substrate and the upper substrate.

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In contradistinction, (U.S. Patent No. 5,973,763), Fujimura et al. disclose that the supporting column is extended vertically to the upper substrate on the lower substrate and the conductive layer is disposed between the upper substrate and the lower substrate including the supporting column. Therefore, the supporting column of Fujimura et al. is different from that claimed by the present invention, which is formed in the same position with the contact hole formed in the common line of the lower substrate. In addition, the conductive layer of Fujimura et al. is formed just on the upper surface of the supporting column, which is a distinguishing feature from the conductive layer of the

presently claimed invention that recites connecting the supporting column and the common line through the contact hole.

With respect to Kurauchi et al., the invention described therein relates to a method for fabricating the supporting column by applying RGB pigments. In contradistinction, the presently claimed invention uses the supporting column to convey the common signal on the lower substrate to the color filter. That is, the present invention provides the common signal to the color filter by connecting the connect hole formed on the common electrodes of the lower substrate through indium tin oxide (ITO) layer. Accordingly, the method of the present invention does not require a conventional dotting process for the interconnection transfer and prevents cross talk by preventing incorrect common signals by providing the common signal at a peripheral region outside an active area of the lower substrate.

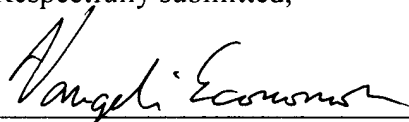
The supporting column of Kurauchi et al. consists of an RGB pattern on the color filter of the upper substrate and is connected to the gate line of the lower substrate. In other words, the supporting column is recited in the present application as being connected to the common line, whereas in that of Kurauchi et al., it is connected to the gate line. Also, the supporting column of the presently claimed invention is connected through the connect hole in the method of inserting, whereas in that of Kurauchi et al., it is connected by contacting the gate line. Therefore, the contact part and connection method of the supporting column are distinguishing features. Also, Kurauchi et al. fails to disclose the feature of a conductive layer as recited in the claims of the present invention.

Additionally, both of the relied upon references fail to show a conductive layer “on the surface” of both the column and the upper substrate. At best, the references disclose a conductive column, that is, a column that is made of a conductive material throughout, and not a conductive layer on the surface of the complete column. More significantly, the references fail to teach a surface layer made of conductive material with which the conductive layer on the column is in

contact to provide a means for signal transmission between the lower substrate and the upper substrate. Since at least these elements are missing from the cited references, it is respectfully suggested that the anticipation rejections under 35 U.S.C. § 102(b) are improper.

For the above reasons, it is considered that the claims, as amended, find support in the parent application specification as filed, and that the combination of elements recited in the pending claims, as amended, distinguish over the references of record. Accordingly, an indication of allowable subject matter is earnestly solicited.

Respectfully submitted,



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